

LIST OF PATENTS AND PUBLICATIONS
FOR APPLICANT(S) INFORMATION
DISCLOSURE STATEMENTAPPLICANTS
Massingill et al.FILING DATE
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U.S. PATENT DOCUMENTS

EX'R INITIAL	*REF. #	PATENT NO.	DATE	NAME	U.S. CLASS/ SUBCLASS	FILING DATE if appropriate)
LT	A1	3,655,540	4/1972	Irvin	204/143 GE	6/1970
	*A2	3,791,858	2/1974	McPherson et al.	117/201	
	A3	3,867,272	2/1975	Rust et al.	204/194	1/1973
	*A4	3,976,524	8/1976	Feng	156/8	
	A5	4,045,312	8/1977	Satoshi	204/129.65	11/1975
	*A6	4,181,755	1/1980	Liu et al.	430/314	
	A7	4,248,683	2/1981	Shaw	204/129.3	4/1980
	*A8	4,614,021	9/1986	Hulseweh	29/590	
	A9	4,729,970	3/1988	Nath et al.	437/225	9/1986
	A10	4,749,454	6/1988	Arya et al.	204/129.3	11/1986
	A11	4,782,028	11/1988	Farrier et al.	437/3	8/1987
	*A12	4,908,940	3/1990	Amano et al.	29/852	
	*A13	4,915,983	4/1990	Lake et al.	427/98	
	*A14	4,921,777	5/1990	Fraenkel et al.	430/314	
	*A15	4,980,034	12/1990	Volfson et al.	437/195	
	A16	4,984,358	1/1991	Nelson	29/830	6/1990
	*A17	5,063,175	11/1991	Broadbent	437/192	
	*A18	5,071,518	12/1991	Pan	205/122	
	*A19	5,091,289	2/1992	Cronin et al.	430/312	
	*A20	5,097,393	3/1992	Nelson et al.	361/386	
	*A21	5,106,461	4/1992	Volfson et al.	205/125	
	*A22	5,118,385	6/1992	Kumar	156/644	
	*A23	5,137,597	8/1992	Curry, II et al.	156/636	
	*A24	5,162,260	11/1992	Leibovitz	427/195	
	A25	5,202,018	4/1993	Horányi et al.	204/129.2	7/1991
	*A26	5,283,081	2/1994	Kata et al.	427/96	
	*A27	5,287,619	2/1994	Smith et al.	29/852	
	*A28	5,316,974	5/1994	Crank	437/190	
	*A29	5,337,466	8/1994	Ishida	29/830	
	*A30	5,464,653	11/1995	Chantraine et al.	427/96	
	*A31	5,512,514	4/1996	Lee	437/195	
	A32	5,543,585	8/1996	Booth et al.	174/261	2/1994
	A33	5,591,678	1/1997	Bendik et al.	437/208	6/1995
	*A34	5,654,237	8/1997	Suguro et al.	438/624	
	A35	5,656,548	8/1997	Zavracky et al.	438/23	9/1995
	A36	5,656,552	8/1997	Hudak et al.	438/15	6/1996
	*A37	5,699,613	12/1997	Chong et al.	29/852	
	A38	5,716,881	2/1998	Liang et al.	438/238	3/1996
	A39	5,734,555	3/1998	McMahon	361/704	3/1994
	A40	5,770,487	6/1998	Mass et al.	438/164	4/1996
	A41	5,784,261	7/1998	Pedder	361/767	1/1996
LT	*A42	5,784,782	7/1998	Boyko et al.	29/848	

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LT	A43	5,807,783	9/1998	Gaul et al.	438/406	10/1996
	A44	5,811,879	9/1998	Akram	257/723	11/1997
	*A45	5,830,533	11/1998	Lin et al.	427/272	
	*A46	5,834,845	11/1998	Stolmeijer	257/752	
	A47	5,838,545	11/1998	Clocher et al.	361/719	10/1996
	A48	5,843,806	12/1998	Tsai	438/107	11/1997
	*A49	5,843,839	12/1998	Ng	438/637	
	A50	5,851,845	12/1998	Wood et al.	438/15	12/1995
	A51	5,856,937	1/1999	Chu et al.	365/51	6/1997
	A52	5,859,397	1/1999	Ichinose et al.	204/157.15	5/1997
	A53	5,863,412	1/1999	Ichinose et al.	205/652	10/1996
	A54	5,863,829	1/1999	Nakayoshi et al.	438/459	11/1996
	A55	5,866,441	2/1999	Pace	438/108	12/1996
	A56	5,872,025	2/1999	Cronin et al.	438/109	3/1997
	A57	5,872,700	2/1999	Collander	361/760	7/1997
	A58	5,877,034	3/1999	Ramm et al.	438/15	9/1995
	*A59	5,891,606	4/1999	Brown	430/312	
	*A60	5,891,799	4/1999	Tsui	438/624	
	*A61	5,916,453	6/1999	Beilin et al.	216/38	
LT	*A62	6,013,417	1/2000	Sebesta et al.	430/312	

FOREIGN PATENT DOCUMENTS

EX'R INITIAL	*REF. #	PATENT NO.	DATE	COUNTRY	CLASS/SUBCLASS	TRANSLATION	
						yes	no
LT	*B1	56-116697	9/1981	JAPAN	3/46	X	
LT	*B2	63-244796	10/12/88	JAPAN	3/46	X	

OTHER ART

EX'R INITIAL	*REF. #	INCLUDE AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.
LT	*C1	Pan et al., "A Planar Approach to High Density Copper-Polyimide Interconnect Fabrication," pp. 174-189, Proceeding of the Technical Conference - 8 th Int'l Electronics Packaging Conference (1988).
LT	*C2	Iwasaki et al., "A Pillar-Shaped Via Structure in a Cu-Polyimide Multilayer Substrate," pp. 127-131, Proceedings of the 1989 Japan International Electronic Manufacturing Technology Symposium.

EXAMINER

Luan Thai

DATE CONSIDERED

12/08/03

EXAMINER:

Initial if reference considered, whether or not citation is in conformance with MPEP 609.
 Draw line through citation if not in conformance and not considered.
 Include copy of this form with next communication to Applicant(s).